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THE WORLDWIDE IC PACKAGING MARKET

2011 EDITION

The Most Comprehensive Report Available On The Global IC Packaging Industry

Report Highlights

- **Industry Overview**
    - **Update on Japan**
    - **Semiconductor Industry Analysis**
- **Worldwide IC Packaging Market Forecasts, 2009–2015**
    - **Units**
    - **Package Prices**
    - **Packaging Revenue**
    - **By Semiconductor Product**
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- **Contract IC Packaging Market Forecasts, 2009–2015**
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    - **Competitive Rankings**
    - **Company Profiles**

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The Worldwide IC Packaging Market, 2011 Edition

Synopsis

The semiconductor industry's recovery in 2010 following the 2008-2009 recession was unprecedented, with one of the best growth years in its history. The estimated worldwide IC growth was 28.9% in terms of units and 31.3% in terms of revenue. Demand is being driven by wireless portable devices such as the iPhone and iPad which is far exceeding the growth of the overall economy.

New Venture Research (NVR), in the **2011 Edition** of **The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market.

The report begins with the latest updates on Japan, mergers and acquisitions, historic and future unit and revenue graphs, and a SATS company overview.

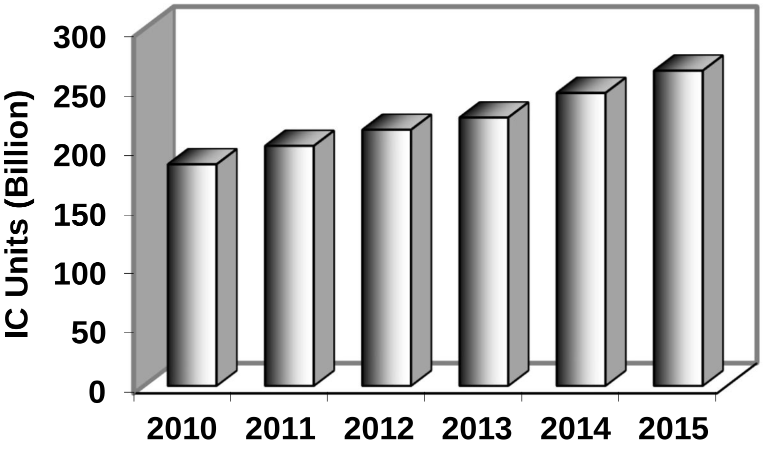

Figure 1 IC Unit Forecast

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents *NVR's* continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

The Worldwide IC Packaging Market, 2011 Edition continues NVR*'s* leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for $2995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for $250 each and a corporate license is $1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional $500.

About the Author

Sandra Winkler is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry more than 20 years ago. Ms. Winkler has authored widely cited reports on IC packaging since 1995 for Electronic Trend Publications (ETP) which is now NVR. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

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